

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Original) A method of manufacturing an electronic circuit, comprising at least one of forming a first pattern and forming a second pattern,
 - forming the first pattern comprising:
 - forming an electrostatic latent image in a predetermined pattern on a first photosensitive base;
 - forming a first visible image on the first photosensitive base on which the electrostatic latent image is formed, by bringing charged particles essentially made of resin into electrostatic adhesion with the first photosensitive base;
 - transferring the first visible image formed on the first photosensitive base onto a first intermediate transfer base, by bringing the first visible image into contact with and pressing the first visible image onto the first intermediate transfer base;
 - forming an integrated resin layer by heating the first visible image transferred onto the first intermediate transfer base to soften the resin constituting the charged particles; and
 - transferring the integrated resin layer onto a first base material by bringing the resin layer into contact with and pressing the resin layer onto the first base material, and
 - forming the second pattern comprising:
 - forming an electrostatic latent image in a predetermined pattern on a second photosensitive base;

forming a second visible image on the second photosensitive base on which the electrostatic latent image is formed, by bringing metal-containing charged particles essentially made of resin and containing metal particulates into electrostatic adhesion with the second photosensitive base;

transferring the second visible image formed on the second photosensitive base onto a second intermediate transfer base, by bringing the second visible image into contact with and pressing the second visible image onto the second intermediate transfer base;

forming an integrated metal-containing resin layer by heating the second visible image transferred onto the second intermediate transfer base to soften the resin constituting the metal-containing charged particles;

transferring the metal-containing resin layer onto a second base material by bringing the metal-containing resin layer into contact with and pressing the metal-containing resin layer onto the second base material; and

forming a conductor metal layer by electroless plating on the metal-containing resin layer transferred onto the second base material.

2. (Original) The method of manufacturing an electronic circuit as set forth in claim 1, wherein forming the first pattern and forming the second pattern are alternately performed once or alternately repeated a plurality of times.

3. (Original) The method of manufacturing an electronic circuit as set forth in claim 1, wherein, in at least one of forming the first pattern and forming the second

pattern, the resin constituting the charged particles or the resin constituting the metal-containing charged particles is B-staged thermosetting resin.

4. (Original) The method of manufacturing an electronic circuit as set forth in claim 1, wherein at least one of forming the first pattern and forming the second pattern further comprises:

curing the resin layer transferred onto the first base material or the metal-containing resin layer transferred onto the second base material by heating or light irradiation.

5. (Original) The method of manufacturing an electronic circuit as set forth in claim 1, wherein at least one of forming the first pattern and forming the second pattern further comprises:

bringing low-melting metal particles into adhesion with the resin layer transferred onto the first base material or the metal-containing resin layer transferred onto the second base material; and

heating and melting the adhering low-melting metal particles.

6. (Currently Amended) The method of manufacturing an electronic circuit as set forth in claim 1, wherein the resin constituting the charged particles adhering on the first photosensitive base or the resin constituting the metal-containing charged particles adhering onto the second photosensitive base contains a fluorescent substance, and

at least one of forming the first pattern and forming the second pattern further comprises judging whether a pattern of the resin containing the fluorescent substance is good enough or not.

7. (Original) A method of manufacturing an electronic circuit comprising at least one of forming a first pattern and forming a second pattern,

forming the first pattern comprising:

forming an electrostatic latent image in a predetermined pattern on a first photosensitive base;

forming a first visible image on the first photosensitive base on which the electrostatic latent image is formed, by bringing charged particles essentially made of resin into electrostatic adhesion with the first photosensitive base; and

transferring the first visible image formed on the first photosensitive base onto a first base material electrostatically, and

forming the second pattern comprising:

forming an electrostatic latent image in a predetermined pattern on a second photosensitive base;

forming a second visible image on the second photosensitive base on which the electrostatic latent image is formed, by bringing metal-containing charged particles essentially made of resin and containing metal particulates into electrostatic adhesion with the second photosensitive base;

transferring the second visible image formed on the second photosensitive base onto a second base material electrostatically; and

forming a conductive metal layer by electroless plating on the second visible image transferred onto the second base material.

8. (Original) The method of manufacturing an electronic circuit as set forth in claim 7, wherein forming the first pattern and forming the second pattern are alternately performed once or alternately repeated a plurality of times.

9. (Original) The method of manufacturing an electronic circuit as set forth in claim 7,

wherein, in at least one of forming the first pattern and forming the second pattern, the resin constituting the charged particles or the resin constituting the metal-containing charged particles is B-staged thermosetting resin.

10. (Original) The method of manufacturing an electronic circuit as set forth in claim 7, wherein at least one of forming the first pattern and forming the second pattern further comprises:

curing the resin contained in the first visible image transferred onto the first base material or the resin contained in the second visible image transferred onto the second base material by heating or light irradiation.

11. (Original) The method of manufacturing an electronic circuit as set forth in claim 7, wherein at least one of forming the first pattern and forming the second pattern further comprises:

bringing low-melting metal particles into adhesion with the first visible image transferred onto the first base material or the second visible image transferred onto the second base material; and

heating and melting the adhering low-melting metal particles.

12. (Currently Amended) The method of manufacturing an electronic circuit as set forth in claim 7,

wherein the resin constituting the charged particles adhering on the first photosensitive base or the resin constituting the metal-containing charged particles adhering on the second photosensitive base contains a fluorescent substance, and

wherein at least one of forming the first pattern and forming the second pattern further comprises judging whether a pattern of the resin containing the fluorescent substance is good enough or not.

13. (Currently Amended) A manufacturing apparatus of an electronic circuit, comprising:

a photosensitive drum;

a mechanism configured to form an electrostatic latent image in a predetermined pattern on the photosensitive drum;

a developing mechanism configured to form a visible image on the photosensitive drum on which the electrostatic latent image is formed, by bringing charged particles essentially made of resin into electrostatic adhesion with the photosensitive drum;

an intermediate transfer drum;

an intermediate transfer mechanism configured to transfer the visible image formed on the photosensitive drum onto the intermediate transfer drum, by bringing the visible image into contact with and pressing the visible image onto the intermediate transfer drum;

a mechanism configured to heat the visible image transferred onto the intermediate transfer drum to soften the resin constituting the charged particles; [[and]]

a base transfer mechanism configured to transfer a layer of the softened resin onto a base material by bringing the layer of the resin into contact with and pressing the layer of the resin onto the base material; and

an electroless plating apparatus in which the resin layer transferred onto the base by the base transfer mechanism is subjected to electroless plating.

14. (Canceled)

15. (Currently Amended) The manufacturing apparatus of an electronic circuit as set forth in claim 13, further comprising:

a pattern ~~recognizing unit~~ inspector configured to recognize a pattern of the resin layer transferred onto the base by the base transfer mechanism.

16. (Currently Amended) The manufacturing apparatus of an electronic circuit as set forth in claim 15, further comprising:

a position correcting ~~mechanism~~ device configured to correct a position of the pattern of the resin layer.

17. (Currently Amended) A manufacturing apparatus of an electronic circuit, comprising:

a photosensitive drum;

a mechanism configured to form an electrostatic latent image in a predetermined pattern on the photosensitive drum;

a developing mechanism configured to form a visible image on the photosensitive drum on which the electrostatic latent image is formed, by bringing charged particles essentially made of resin into electrostatic adhesion with the photosensitive drum; [[and]]

a base transfer mechanism configured to transfer onto a base material the visible image formed on the photosensitive drum electrostatically; and

an electroless plating apparatus in which the visible image transferred onto the base by the base transfer mechanism is subjected to electroless plating.

18. (Canceled)

19. (Currently Amended) The manufacturing apparatus of an electronic circuit as set forth in claim 17, further comprising:

a pattern ~~recognizing unit~~ inspector configured to recognize a pattern of the visible image transferred onto the base by the base transfer mechanism.

20. (Currently Amended) The manufacturing apparatus of an electronic circuit as set forth in claim 19, further comprising:

a position correcting mechanism device configured to correct a position of the pattern of the visible image.

21. (New) The method of manufacturing an electronic circuit as set forth in claim 1, wherein, in forming the second pattern, after a part of the metal-containing resin layer transferred onto the second base material is removed by etching, the conductor metal layer is formed on the metal-containing resin layer by electroless plating.

22. (New) The method of manufacturing an electronic circuit as set forth in claim 1, wherein at least one of forming the first pattern and forming the second pattern has adding a new pattern or correcting a position of the pattern formed.

23. (New) The method of manufacturing an electronic circuit as set forth in claim 7, wherein, in forming the second pattern, after a part of the second visible image transferred onto the second base material is removed by etching, the conductor metal layer is formed on the second visible image by electroless plating.

24. (New) The method of manufacturing an electronic circuit as set forth in claim 7, wherein at least one of forming the first pattern and forming the second pattern has adding a new pattern or correcting a position of the pattern formed.